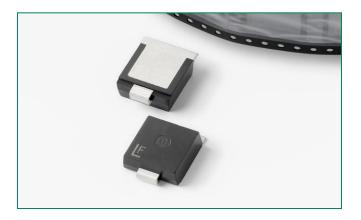


LTKAK10 Series







Description

The LTKAK10 series offer superior clamping characteristics over standard S.A.D. technologies by virtue of the Littelfuse Foldbak technology, which provides a clamping voltage lower than the avalanche voltage (but above the rated working voltage). Therefore, any voltage rise due to increased current conduction is contained to a minimum, providing the best possible protection level. They can also be connected in series and/or parallel to create various capability and flexible protection solutions.

The LTKAK10 SMT package provides a more compact PCB layout than typical through-hole AKTVS components.

Agency Approvals

AGENCY	AGENCY FILE NUMBER
71	E128662

Features

- High Power TVS designed in a surface mount compact SMTO-218 package
- Patent pending package design
- Foldbak technology for superior clamping factor
- Tube or tape and reel pack options available
- Ideal for automatic pick and place assembly and reflow process to reduce the manufacturing cost and increase the soldering quality as compared to axial leaded packages
- Bi-directional

- Meet MSL level 1, per J-STD-020, LF maximun peak of 260°C
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)
- UL Recognized compound meeting flammability rating V-0

Maximum Ratings and Thermal Characteristics (T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating Junction	T _J	-55 to 125	°C
Storage Temperature Range	T _{stg}	-55 to 150	
Current Rating ¹	I _{PP}	10	kA
Typical Thermal Resistance Junction to Lead	R _{eJL}	10	°C/W
Typical Thermal Resistance Junction to Ambient	R _{eJL}	50	°C/W

1. Rated min I_{np} measured with 8/20µs pulse.

Functional Diagram



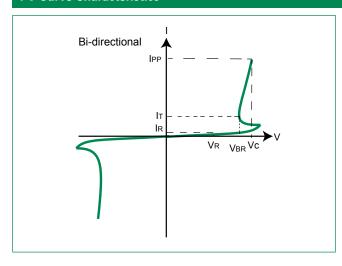
Electrical Characteristics

Part	Standoff Max. Reverse	Voltage (V _{BR}) @ I _T		Test Current I _T	Max. Clamping Voltage V _{CL} @ Peak Pulse Current (I _{PP})			Max. Temp Coefficient of V _{BR}	Max. Capacitance 0V Bias 10kHz	Agency Approval		
Numbers (V _{so}) (V)		Leakage (I _R) @V _{so} (µA)	Min Volts	Max Volts	(mA)	V _{CL} Volts	Ι _{ΡΡ} (8/20μs) (A)	(10/3	50µs) 4)	(%/°C)	(nF)	<i>91</i> .
							min	min	typ			
LTKAK10-058C	58	10	64	70	10	110	10,000	1,400	1,700	0.1	8.5	X
LTKAK10-066C	66	10	72	80	10	120	10,000	950	1,100	0.1	7.5	-
LTKAK10-076C	76	10	85	95	10	140	10,000	1,400	1,700	0.1	6.5	Х
LTKAK10-086C	86	10	95	105	10	157	10,000	1,000	1,200	0.1	6.5	-

Note: Using 8/20 waveshape as defined in IEC 61000-4-5 2nd edition.



I-V Curve Characteristics



$\mathbf{P}_{\scriptscriptstyle{\mathrm{PPM}}}$ Peak Pulse Power Dissipation -

Max power dissipation

V_s Stand-off Voltage -

Maximum voltage that can be applied to the TVS without operation

V_{BR} Breakdown Voltage --

Maximum voltage that flows though the TVS at a specified test current (I,)

V. Clamping Voltage -

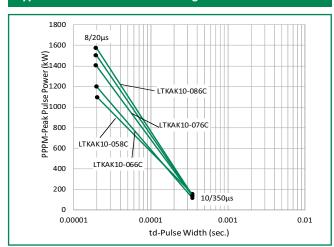
Peak voltage measured across the TVS at a specified lppm (peak impulse current)

I Reverse Leakage Current --

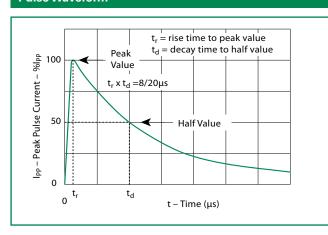
Current measured at V_R

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

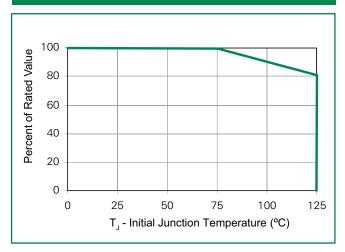
Typical Peak Pulse Power Rating Curve



Pulse Waveform



Peak Power Derating

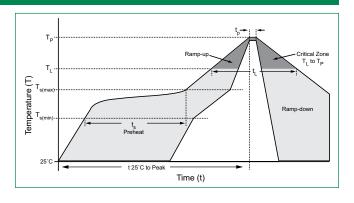


Please contact Littelfuse for reliability or FIT/MTBF data, the component's performance is dependent on the application's environmental conditions such as elevated ambient temperatures.



Soldering Parameters

Reflow Cor	ndition	Lead-free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (min to max) (t _s)	60 – 180 secs	
Average ra to peak	mp up rate (Liquidus Temp (T _A)	3°C/second max	
T _{S(max)} to T _A	- Ramp-up Rate	3°C/second max	
Reflow	-Temperature (T _A) (Liquidus)	217°C	
	-Time (min to max) (t _s)	60 – 150 seconds	
Peak Temp	erature (T _P)	260 ^{+0/-5} °C	
Time within	n 5°C of actual peak re (t _p)	20 – 40 seconds	
Ramp-dow	n Rate	6°C/second max	
Time 25°C	to peak Temperature (T _P)	8 minutes Max.	
Do not exc	eed	260°C	



Flow/Wave Soldering (Solder Dipping)

Peak Temperature :	265°C
Dipping Time :	10 seconds
Soldering :	1 time

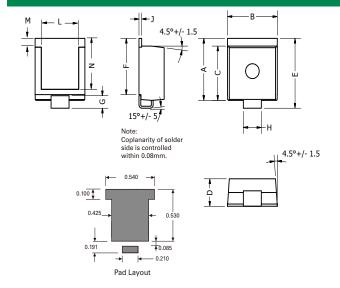
Physical Specifications

Weight	Contact manufacturer		
Case	Compound encapsulated		
Terminal	Tin plated lead, solderable per MIL-STD-202 Method 208		

Environmental Specifications

High Temp. Storage	JESD22-A103	
HTRB	JESD22-A108	
MSL	JESDEC-J-STD-020, Level 1	
H3TRB	JESD22-A101	
RSH	JESD22-B106	

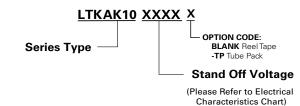
Dimensions — SMTO-218 Tab



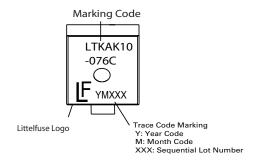
Dimension	Inc	hes	Millimeters		
Dimension	Min	Max	Min	Max	
А	0.621	0.655	15.78	16.63	
В	0.529	0.594	13.43	15.09	
С	0.544	0.561	13.83	14.24	
D	0.273	0.285	6.94	7.24	
Е	0.702	0.737	17.82	18.72	
F	0.567	0.587	14.40	14.90	
G	0.087	0.126	2.20	3.20	
Н	0.193	0.222	4.89	5.65	
J	0.028	0.033	0.72	0.85	
L	0.400	0.440	10.17	11.17	
M	0.073	0.112	1.85	2.85	
N	0.510	0.533	12.95	13.55	



Part Numbering System



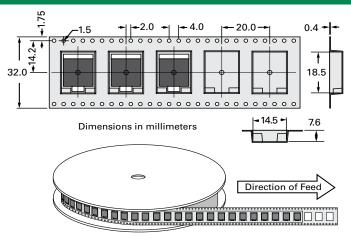
Part Marking System



Packaging

Part Number	Weight	Packing Mode	Base Quantity
LTKAK10-xxxC	4.34g	Tape & Reel – 32mm/13" tape	400
LTKAK10-xxxC-TP	4.34g	Tube Pack	100(25/Tube)

Tape and Reel Specification



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